consemi Contact Name Title - Contact Product-Env-Stewards Product-Enviro Compliance Authorized Representative* Title - Representative Phone - Contact* Email - Contact* Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com Email - Representative* Email - Representative*	PC SOCIATION CONNECTING ECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID Unique ID Authority Description De	2-21.1					e *					als and Mfg	Informati	on		
Insemi Insemi Inse	pplier Informa	ation								,					
Title - Contact Name Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Pro	Company name*			Company unique ID			ī	Unique ID Authority				Response Date*			
Product-Env-Stewards Authorized Representative* Authorized Representative* Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Phone - Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com NA NA NA NA NA NA NA NA Nanufacturing Site Weight* UOM NVMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM 2024-04-26 MY1 136.09 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	emi											2024-04-26			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number NA Requester Item Number NVMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM Product-Env-Stewards NA NYMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM NVMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM Product-Env-Stewards@onsemi.com NM1 NVMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM NVMFD5875NLT1G NVMFD5875	ıtact Name		Title - Contact				Phone - Contact*				Email - Contact*				
Product-Env-Stewards Requester Item Number Mfr	oduct-Env-Stewar	ards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM NVMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM 2024-04-26 MY1 136.09 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	horized Represen	ntative*	Title - Representative]	Phone - Representative*				Email - Representative*				
NVMFD5875NLT1G NFET SO8FL 60V 22A 33MOHM 2024-04-26 MY1 136.09 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	oduct-Env-Stewar	ırds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester Item Number		Mfr Item Number		Mfr Item Name			Effective Date	Version	rsion Manufacturing Site		W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			NVMFD5875NLT1G NFET SC		NFET SO8FL 60V	ET SO8FL 60V 22A 33MOHM		2024-04-26	26 MY1		13	86.09	mg	Each	
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3				arminal Rasa	Alloy	STD 020 MS	I Dating	Pagk Progr	es Rody Tar	nnaratur	May Time at Peak	Tamparatu	ra Numb	ar of Paflow Cyc	das
				•		31D-020 M3	L Kaung							ei oi Keilow Cyc	ies
OHIHICHIS	•	ii (Sii) - aimeaieu	C	O Anoy	1			200		<u> </u>	30	second	5 3		
evel 1 - maximum time at peak temperature during soldering is 10-30 seconds		ime at neels temperatur	o during sol	doring is 10.2	O soconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content is the content of	sess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- nce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certification conditions of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.76	mg	Supplier	Silicon (Si)	7440-21-3		6.76	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			A	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	83.05	mg	Supplier	Iron (Fe)	7439-89-6		0.5814	mg
			Supplier	Copper (Cu)	7440-50-8		82.4687	mg
Mold Compound-Black	33.33	mg		Epoxy Phenol Resin	proprietary data		3.4997	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.8304	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.95	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg